



13.6
- 10.0
4.2762

BOX RCE

February 4, 2002
[Note: February 2, 2002
was a Saturday]

Sir:

Please amend the above-identified application as follows.

RECEIVED
FEB 26 2002
TC 1700

Please amend claims 2, 20, 29, and 36 as follows.

2. ^{twice} (Amended) A method for manufacturing a semiconductor device comprising steps of:

forming a semiconductor film over a substrate; and

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231

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